











- Custom formulations to meet stringent process requirements
- Dedicated and knowledgeable technical support
- ISO 9001:2015 certification to ensure consistent, premier quality products and service



PRODUCT SELECTOR CHART

High Performance Encapsulant, Overlaminant, Adhesive and Specialty Compounds

CUSTOM FORMULATIONS







SINCE 1980





EPMAR Corporation 13240 Barton Circle Whittier, CA 90605

> P: 562.946.8781 F: 562.944.9958

> > epmar.com



PRODUCT SELECTOR CHART:

HIGH PERFORMANCE ENCAPSULANT, OVERLAMINANT, ADHESIVE AND SPECIALTY COMPOUNDS

		MIX RATIO (A:B)	MIXED VISCOSITY CPS AT 25°C	POT LIFE AT 25°C 100G MASS	CURE SCHEDULE	SPECIFIC GRAVITY	HARDNESS SHORE	GLASS TRANSITION TEMP	DIELECTRIC STRENGTH V/MM	VOLUME RESISTIVITY (OHM-CM)
EPOX	Y ELECTRICAL ENCAPSULANTS									
SS1803	Two component black, low viscosity electronic grade potting compound. Excellent physical and electrical characteristics combined with easy handling make this resin/hardener combination ideal for the encapsulation of electronic modules. Surface appearance: High gloss	100:42 BY WEIGHT	995	40 MINUTES	24 HRS AT RT OR 3 HRS AT 60°C	1.12	D: 85	65°C	540	3.1 X 10 ¹⁵
SS1804	Two component black, filled room temperature curing epoxy potting compound. Developed for electronic module potting applications. Excellent electrical and physical properties combined with easy handling, self deaeration. Surface appearance: High gloss	100:30 BY WEIGHT	890	1 HOUR	24 HRS AT RT OR 3 HRS AT 60°C	1.19	D: 80	66°C	510	4.6 X 10 ¹⁴
SS1 836 X-1	Two component black, filled epoxy compound. Developed for electronic module potting applications. Excellent thermal properties, low shrinkage and lower coefficient of thermal expansion.	100:100 OR 1:1 By Volume	10,600	2 HOURS	24 HRS AT RT OR 3 HRS AT 60°C	1.52	D: 76	40°C	410	3.0 X 10 ¹⁴
SS1873	Two component black, filled epoxy compound. The compound consists of a filled resin and filled hardener. Developed for electrical and electronic module potting applications. Exhibits outstanding tensile strength and crack resistance under extreme conditions.	100:100 OR 1:1 BY VOLUME	4720	90 MINUTES	24 - 36 HRS AT RT OR 3 HRS AT 60°C	1.61	D: 85	40°C	500	1.5 X 10 ¹⁴
SS1874	Two component clear, room temperature curing epoxy compound. Developed for applications requiring a clear casting compound. Excellent electrical and physical properties. Surface appearance: Clear Casting	100:42 BY WEIGHT	760	1 HOUR	7 DAYS AT RT OR 4 HRS AT 80°C	1.10	D: 80	68°C	515	3.1 X 10 ¹⁴
SS1875	Two component black, filled epoxy compound. The compound consists of a filled resin and filled hardener. Developed for electrical and electronic module potting applications. Excellent thermal properties, low shrinkage and lower coefficient of thermal expansion.	100:100 OR 1:1 By volume	6590	90 MINUTES	24 - 36 HRS AT RT OR 3 HRS AT 60°C	1.61	D: 87	42°C	500	1.5 X 10 ¹⁴
SS1 92 0	Two component white or black, heat cure epoxy compound. Developed for electronic component and circuitry potting and encapsulation applications. Flame retardant compound containing no halogens or antimony oxide. Formulated for the fly back transformer market. UL listed 94VO. Surface appearance: Gloss	100:35 BY WEIGHT	1090	8 HOURS	90 MIN AT 70°C PLUS 3 HRS AT 115°C	1.61	D: 90	114°C	560	5.9 X 10 ¹⁴
S02820	Single component gray, heat cure epoxy. Developed for filter adhesive applications. This high performance compound resists extensive solvent submersion tests and exhibits excellent thermal shock resistance. Passes Mil Spec testing.	NA	30,000	NA	15 MIN AT 120°C PLUS 15 MIN AT 175°C	1.60	D: 93	91°C	NA	NA
EPOX	Y OVERLAMINANTS									
SS1919	Two component clear amber, low viscosity 100% solids epoxy system. NSF 61 approved. Excellent adhesion to most substrates and has high chemical resistance. Formulated for the filter market. Surface appearance: High Gloss	100:40 BY WEIGHT	750	10 MINUTES	24 HRS AT RT OR 4 HRS AT 80°C	1.09	D: 90	57°C	520	8.0 X 10 ¹⁴
SS1933	Two component clear amber, low viscosity 100% solids epoxy system. NSF 61 approved. Excellent adhesion to most substrates and has high chemical resistance. Formulated for the filter market. Surface appearance: Good Gloss	2:1 BY VOLUME	900	30 MINUTES	24 HRS AT RT OR 4 HRS AT 60°C	1.1	D: 85	NA	NA	NA
SS1 93 4	Two component clear amber, low viscosity 100% solids epoxy system. NSF 61 approved. Excellent adhesion to most substrates and has high chemical resistance. Formulated for the filter market. Surface appearance: Good Gloss	2:1 BY VOLUME	900	30 MINUTES	24 HRS AT RT OR 4 HOURS AT 60°C	1.1	D: 85	NA	NA	NA
POLY	JRETHANE ADHESIVE									
SS2120	Two component white, membrane adhesive. Developed for RO and dairy filter applications. This high performance adhesive exhibits high PH and temperature resistance, while providing outstanding yields. FDA 175.105 compliant. NSF 61 approved filters.	1:1 BY VOLUME	20,000	30 MINUTES	5 DAYS AT 25°C OR 3 HRS AT 60°C	1.05	D: 45	NA	NA	NA
POLY	JRETHANE ENCAPSULANTS									
SS2017	Two component green, unfilled, 100% solids MDI based polyurethane compound. Developed for telecommunications connector block potting and casting applications.	100:150 BY Weight	825	12 MINUTES	GEL: 18 MIN AT RT 7 - 10 DAYS AT RT OR 3 HRS AT 60°C	1.10	D: 60	-80°C	480	3.1 X 10 ¹³
SS2044	Two component clear, polyurethane compound. This high performance, flexible compound exhibits outstanding environmental thermal cycling resistance and provides excellent resistance to moisture exposure.	1:1 BY VOLUME	650	20 MINUTES	5 - 7 DAYS AT 25°C OR 4 HRS AT 60°C	1.00	D: 45	NA	1.01	1.1 X 10 ¹¹
SS2055	Two component black, polyurethane compound. This high performance, flexible compound exhibits excellent water resistance and low shrinkage. UL 94HB.	20:100 BY WEIGHT	650	60 MINUTES	7 DAYS AT 25°C OR 16 HRS AT 165°C	1.4	D: 45	NA	NA	NA
SS2125	Two component white, polyurethane compound. This high performance compound was developed for HEPA filter applications.	1:1 BY WEIGHT	600	4 MINUTES	5 - 7 DAYS AT RT OR 3 HRS AT 60°C	1.1	A: 70	NA	NA	NA
SPECI	ALTY POLYURETHANES									
SS 20 14	Two component gray, polyurethane compound with a long cream time. This hard, rigid foam can be hand or machine processed. The tough, hard skin makes this foam ideal for use in fabricating artificial rocks, picture frames, decorative accents and similar applications. Available in densities of 2 pcf - 30 pcf.	52:48 BY WEIGHT	NA	CREAM TIME: 2 MIN.	GEL: 10 MIN AT RT 24 HRS AT RT	NA	D: 32	NA	NA	NA
SS2105	Two component gray or tan, polyurethane and polyurea hybrid system. The compound consists of a MDI base prepolymer component and a amine and polyether polyol component. This sprayable compound is formulated to produce good chemical and moisture resistance. Designed for spraying and fast demold time. Casting version available.	52.3:47.7 BY WEIGHT	NA	6 SECONDS	GEL: 12 SEC AT RT 24 HRS AT RT	1.06	A: 80	NA	NA	NA
SS 2056	Two component amber, polyurethane elastomer system. The compound consists of a MDI base prepolymer component and a polyester polyols component. This pourable compound is formulated to produce good chemical resistance and physical properties. Developed for electronic device applications.	52.3:47.7 BY WEIGHT	NA	2 MINUTES	GEL: 3 MIN AT RT 24 HRS AT RT	1.17	A: 60 - 65	NA	NA	NA